

IN THE CLAIMS

1. (Currently amended) A method of packaging components, comprising:
~~bending a carrier to~~forming an enclosure including a plurality of covers having an air-cavity ~~to receive at least one of the components therein,~~ each of said covers comprising a vent hole;
mounting a plurality of components a carrier;
applying a curable adhesive between said enclosure and said carrier,
aligning said enclosure with the carrier such that each component is covered by one of said air-cavity covers;
curing said adhesive, said vent hole providing for the escape of water and other gasses that may off-gas during the curing process from said air cavity;
sealing said vent holes with a curable material;
curing said sealing material; and
separating the enclosure and carrier to form a plurality of
~~forming a component package assemblies assembly.~~
2. (Original) The method of claim 1, wherein the components comprise at least one component die.
3. (Original) The method of claim 1, wherein the enclosure is formed of materials comprising polymers, ceramic, glass, and combinations thereof.
4. (Currently amended) The method of claim 1, wherein forming
~~bending~~ comprises molding. ~~providing an adhesive layer~~

~~between the enclosure and the carrier.~~

5. (Currently amended) The method of claim 4~~1~~, wherein providing the adhesive ~~layer~~ between the enclosure and the carrier comprises applying an adhesive to the carrier.
6. (Currently amended) The method of claim 4~~1~~, wherein providing an adhesive ~~layer~~ between the enclosure and the carrier comprises applying adhesive to a cover surface disposed adjacent the carrier.
7. (Currently amended) The method of claim 1, ~~further comprising separating the component package assembly into a plurality of individual component packages~~wherein each of said covers comprises sidewalls.
8. (Original) The method of claim 7, wherein separating comprises cutting between each of the pluralities of component through a plurality of sidewalls and the carrier.
9. (Original) The method of claim 8, wherein cutting comprises sawing, laser cutting, water cutting, milling, machining, lathing, and combinations thereof.
10. (Canceled) ~~A method of packaging components, comprising:

bonding a body including a plurality of component covers to
a carrier comprising a plurality of the components
thereon wherein at least one of the components is~~

~~positioned proximate one of the component covers; and~~
~~providing an air cavity between the components and a~~
~~respective component covers.~~

11. ~~(Canceled) The method of claim 10, wherein the components comprise an component die.~~
12. ~~(Canceled) The method of claim 10, wherein the body is formed of materials comprising polymers, ceramic, glass, and combinations thereof.~~
13. ~~(Canceled) The method of claim 10, wherein the body comprises sidewalls defining the component covers.~~
14. ~~(Canceled) The method of claim 13, wherein bonding the body to the carrier comprises providing an adhesive between the sidewalls and the carrier.~~
15. ~~(Canceled) The method of claim 10, further comprising separating the sidewalls and carrier to form individual components having at least one of the plurality of covers thereon.~~

16. ~~(Canceled) The method of claim 15, wherein separating comprises sawing the common sidewalls and carrier using a saw, laser cutting tool, water cutting tool, mill, lath, and combinations thereof.~~
17. ~~(Canceled) The method of claim 10, wherein providing the air cavity between each of the components and their respective component covers comprises forming the sidewalls with a top portion that exceeds the height of the components.~~
18. ~~(Canceled) The method of claim 17, wherein the sidewalls and the top portion define an enclosure.~~
19. (Withdrawn) An apparatus for enclosing at least one component, comprising:

a plurality of separable sidewalls disposed on a top member
wherein the separable sidewalls and top member define a plurality of separable individual component packages to enclose the at least one component therein.
20. (Withdrawn) The apparatus of claim 19, wherein when separated, the sidewalls and top member define an individual component enclosure.